More details her

IoT SuperServer SYS-220HE-FTNR

Key Applications

5G Core and Edge, Telecom Micro Data Center, AI Inference and Machine Learning, Network Function Virtualization, Cloud Computing,

Key Features

- Dual Socket P+ (LGA-4189) 3rd Gen Intel[®] Xeon[®] Scalable Processors;
- 32 DIMM Slots; Up to 8TB DRAM; Up to 8TB Intel[®] Optane[™] Persistent Memory (up to 12TB with DRAM); 3200/2933/2666 ECC DDR4 LRDIMM;RDIMM; Intel[®] Optane[™] Persistent Memory 200 series;
- 3 PCIe 4.0 x16 slots with GPU/Accelerator support (Default); 1 PCIe 4.0 x16 expansion slots (Optional);
- Flexible networking options with 2 AIOM networking slots (OCP NIC 3.0 compatible);
- Up to 6x 2.5" hot-swap drive bays with options to support NVMe/SATA drives;
- 6 heavy duty hot-swap fans with optimal fan speed control Front I/O, toolless design;
- Redundant 2000W redundant AC power supplies;



2U Rackmount
Enclosure: 436.88 x 88.9 x 574mm (17.2" x 3.5" x 22.6")
Package: 598 x 247 x 938mm (23.5" x 9.7" x 36.9")
3rd Gen Intel® Xeon® Scalable processors
Dual Socket LGA-4189 (Socket P+) supported
TDP up to 270W; 3 UPI
32 DIMM slots
Up to 8TB ECC LRDIMM, DDR4-3200MHz
Up to 8TB Intel [®] DCPMM, DDR4-3200MHz
Up to 8TB ECC RDIMM, DDR4-3200MHz
6x 2.5" hot-swap NVMe/SATA drive bays (6x 2.5" NVMe hybrid)
2 M.2 NVMe OR 2 M.2 SATA3
M-Key, 2280/22110
3 PCIe 4.0 x16 or x8 FHFL slot(s)
1 PCIe 4.0 x8 FHFL slot(s)
2 PCIe 4.0 x8FHFL slot(s)
1 PCIe 4.0 x8 or (Optional) x16 FHHL slot(s)
1 PCIe 4.0 x8 FHHL or slot(s)
Note:
If Slot 1 is configured as PCIe x16, Slot 2 will be disabled; If Slot 3 is configured as PCIe x16, Slot 4 will be disabled;
If Slot 5 is configured as PCIe x16, Slot 6 will be disabled; (Optional) If Slot 7 is configured as PCIe x16, Slot 8 will be
disabled.
SATA: SATA3 (6Gbps); RAID 0/1/5/10 support
NVMe: NVMe; RAID 0/1/5/10 support (Intel [®] VROC RAID Key required)
Chipset: Intel® C621A
Network Connectivity: 2x 1GbE BaseT with Intel [®] i350-AM2 (optional)
4x 1GbE SFP or 2x 10GbE BaseT with Intel [®] X550-AT2 (optional)
2x 10GbE SFP+ with Intel [®] X710-BM2 (optional)
4x 10GbE SFP+ with Intel [®] XL710-BM1 (optional)
4x 10GbE RJ45/SFP+ with Intel [®] X710-TM4 (optional)
2x 25GbE SFP28 with Broadcom [®] BCM57414 (optional)
4x 25GbE RJ45/SFP28 with Mellanox [®] CX-4 Lx EN Intel [®] X550-AT2 (optional)
2x 100GbE QSFP28 with Broadcom® BCM57508 (optional)
4x 1GbE BaseT with Intel® i350-AM4 (optional)
IPMI: Support for Intelligent Platform Management Interface v.2.0
IPMI 2.0 with virtual media over LAN and KVM-over-LAN support

Input / Output

LAN: 1 RJ45 Dedicated BMC LAN port USB: 2 USB 2.0 port(s) (2 front) Video: 1 VGA port(s)

	(Front View – System)			(Rear View - System)
a LEDa DO				
Redundant 200 Titanium Level P Stot Descri	ower Supplies 2 USB 3 0 P	Ports		<mark>a de de de de d</mark> e de de
AOM LOCK				
ALOM / DOS	FAIC 3.0 Stot			
Acom / Och Dynamic Pr	NG 3 8 Sec. SHE 4 6 M ² (m x16) Shel IV POLE 4 6 V15 Sul (FH: 18.51)		Stor	Description
Acom / Ocs Dystem Pt Optional Pt	1 GC 3 6 Sec. 5 E 4 6 J4 (m. x19) Sed J7 PD E 4 8 v13 Sed (FH. 13 51.) 5 E 4 8 x1 (m. x19) Sec (FH. 18 51.)		Slot	Description 2.55 Hot swam NOM/#SAS3/ISATA3 Draw Rays (NVMs from CPU1)**
AcOM / OCS DptMod/ PS DptMod/ PS DptMod/ PS DptMod/ PS DptMod/ PS	1902 3 0 500 DE 4 6 xd (m. x04) 564 (x POLE 4 6 x15 564 (PH. 15 51) DE 4 8 xd (m. x16) 564 (PH. 10 51) DE 4 8 xd (m. x16) 564 of PDE 4 8 x16 564 (PH. 10 51)		Slot	2.5" Hot-swap NVMe/SAS31/SATA3 Drive Bays (NVMe from CPU1)**
AcOM / OCS Dpticeal Pt	* RC 30 50x DE 4 4 년 (K, KM) 564 (JP PDE 4 4 4 K) 564 (PH - 12 51) DE 4 4 9 년 (K, KM) 564 (PH - 10 51) DE 4 4 9 년 (K, KM) 566 (PH - 10 51) DE 4 4 9 년 (K, KM) 566 (PH - 10 51)			
Acon / OCF Dekideli Pi Cytiqual Pi Cytiqual Pi Depiced Pi Depiced Pi Depiced Pi Depiced Pi Depiced Pi Depiced Pi	190 3 8 04 36 4 3 6 04 36 4 4 6 04 5 6 04 5 04 6 7 0 5 1 4 5 1 5 1 4 5 1 1 26 4 5 6 04 1 5 04 7 1 4 5 1 1 26 4 5 6 04 1 5 04 7 1 4 5 1 1 26 4 5 6 04 1 5 04 1 1 5 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1		<u>e</u> - (25' Hotswap NVMe/SAS3'/SATA3 Drive Bays (NVMe from CPU1)* 25' Hotswap NVMe/SAS3'/SATA3 Drive Bays (NVMe from CPU2)*
Active / occ A	190 3 9 0x 54 8 0 m × 105 0 m / PD & 4 8 405 0 m / PH × 105 1/ 54 8 4 m × 105 0 m / PD & 4 8 405 0 m / PH × 105 1/ 54 8 4 m / H × 105 0 m / PD & 4 8 415 0 m / PH × 105 1/ 54 8 4 m / H × 105 0 m / PD & 4 8 415 0 m / PH × 105 1/ 1 m × 105 0 m / PD & 4 8 415 0 m / PH × 105 1/ 1 m × 105 0 m / PD & 4 5 415 0 m / PH × 105 1/ 0 m × 105 0 m / PH × 105 1/		<u>e</u> - (2.5" Hot-swap NVMe/SAS31/SATA3 Drive Bays (NVMe from CPU1)**
ACM / DCS Delevant PC Optional PC	190 3 8 04 36 4 3 6 04 36 4 4 6 04 5 6 04 5 04 6 7 0 5 1 4 5 1 5 1 4 5 1 1 26 4 5 6 04 1 5 04 7 1 4 5 1 1 26 4 5 6 04 1 5 04 7 1 4 5 1 1 26 4 5 6 04 1 5 04 1 1 5 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1		<u>e</u> - (25' Hotswap NVMe/SAS3'/SATA3 Drive Bays (NVMe from CPU1)* 25' Hotswap NVMe/SAS3'/SATA3 Drive Bays (NVMe from CPU2)*

System Cooling	6 heavy duty fan(s)
Power Supply	2000W 1U Redundant Power Supply Reverse airflow vs PWS-2K08A-1R Dimension (W x H x L): 73.5 x 40 x 203 mm
System BIOS	BIOS Type: AMI 256MB SPI Flash
Management	IPMI 2.0; SuperDoctor® 5; Watch Dog; NMI; KVM with dedicated LAN; Intel® Node Manager; Redfish API; SPM; SUM; SSM
PC Health Monitoring	CPU: Monitors for CPU Cores, Chipset Voltages, Memory
	FAN: Fans with tachometer monitoring
	Status monitor for speed control
	Pulse Width Modulated (PWM) fan connectors Temperature: Monitoring for CPU and chassis environment
	Thermal Control for fan connectors
Dimensions and Weight	Height: 3.5" (88.9 mm)
	Width: 17.2" (436.88 mm)
	Depth: 22.6" (574 mm)
	Gross Weight: 47.4 lbs (21.5 kg)
	Net Weight: 34.4 lbs (15.6 kg)
	Packaging: 9.7" (H) x 23.5" (W) x 36.9" (D) Available Color: Silver
Operating Environment	Operating Temperature: 5°C ~ 35°C (41°F ~ 95°F)
	Non-operating Temperature: -40°C to 70°C (-40°F to 158°F)
	Operating Relative Humidity: 8% to 90% (non-condensing)
	Non-operating Relative Humidity: 5% to 95% (non-condensing)
Motherboard	Super X12DHM-6
Chassis	CSE-HE211-R000NFP